TECHNICAL BULLETIN

ALPHA FLUITIN 1532 No Clean Cored Solder wire

Type: J-STD-004 - ROM1 / IPC-SF-818-M3CN / ISO 12224 - 1.1.2 / DIN 8511-F-SW26

DESCRIPTION

Alpha Fluitin 1532 is an activated rosin cored solder wire developed for general hand soldering applications. The unique activator system offers good thermal stability at pre-soldering temperatures ensuring that Fluitin 1532 performs extremely well on parts and surfaces which present poor or difficult soldering conditions.

Fluitin 1532 leaves post-soldering residues that are hard and which can be safely left without the need to remove them. If the removal of residues is required then semi-aqueous or aqueous systems can be used effectively.

FEATURES & BENEFITS

- Minimal, non-corrosive, clear and safe residues.
- Very fast wetting.
- Good spread characteristics.
- Pleasant pine smell.
- Ease of solderability.
- Provides good joint appearance.

APPLICATION

Fluitin 1532 is suitable for use in any commercial no-clean hand soldering application that specifies compliance to J-STD-004 – ROM1 standard.

It is suited to such areas of industry (subject to the above criteria) as TV, Audio equipment, Video/DVD, Games box and all types of household appliances.

HINTS & TIPS ON SOLDERING IN GENERAL

Always remember that a soldered joint is formed by heating the parts to be soldered to a temperature in excess of the melting point of the alloy to be used – in hand soldering this is how a soldering iron is used. By feeding the cored wire onto the parts, the flux is able to flow and remove oxide films, whilst the solder creates a thin intermetallic bond which becomes the solder joint. Note the following tips:

- Use a soldering iron bit size and form to suit the operation: small bits for soldering large components may prevent the formation
 of a joint or slow the process down.
- Always select wire diameters to suit both soldering iron bit and the parts/components to be soldered.
- Soldering irons systems should provide sufficient heat to satisfy the requirements of the points above.
- Cored solder wires can be provided in different grades of alloy so always ensure you have selected the right grade for the application.
- Do not overheat as this causes an increase in the depth of the intermetallic layer, which in turn weakens the joint.

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Cookson Electronics ASSEMBLY MATERIALS



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All materials from Cookson Electronics Assembly Material are manufactured to meet the most stringent of standards and to ensure the best possible finish to every soldering application.

TECHNICAL SPECIFICATION

Physical Properties	Typical Values		
Rosin Grade:	WW per Fed Spec. LL-R-626		
Rosin Softening Point:	71°C (160°F)		
Acid Value:	170-190 (mg KOH/g)		
Halide Content:	0.80 – 1.10% (by weight)		
Corrosiveness:	Classified to J-STD-004 as M type material		
Copper Mirror:	Classified to J-STD-004 as <50% breakthrough		
Surface Insulation Resistance: (Not Cleaned)	Passes IPC-SF-818 Class III. Test results to J-STD-004 85°C/85% RH / 7 days CD = 4.7E10 Ohms CU = 5.9E09 Ohms (Pass > 1E08 Ohms)		
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Standard	Alloy Designation	Melting or Solidus / Liquidus Temp °C	Flux Configuration
ISO 9453 (1)	-Sn63Pb37	183	1.1% & 2.2%
ISO 9453 (2)	S-Sn60Pb40	183 - 190	1.1% & 2.2%
ISO 9453 (25)	S-Sn60Pb38Cu2	183 - 190	1.1% & 2.2%
ISO 9453 (30)	S-SN62Pb36Ag2	178 - 190	2.2%
LEAD FREE	SAC 305 LEAD FREE	217	2.2% & 3.3%
LEAD FREE	SACX0307 LEAD FREE	217 - 228	2.2% & 3.3%
LEAD FREE	SAC 405	217-219	2.2% & 3.3%

HEALTH & SAFETY

Observe standard precautions for handling and use. Use in well ventilated areas. DO NOT SMOKE.

Alpha Fluitin 1532 wire is not considered toxic. However, its use in typical soldering applications will generate a small amount of decomposition and fumes.

These fumes must adequately exhausted/vented for operator safety and comfort.

In order to carry out your full COSHH assessment, consult the product Material Safety Data Sheet (MSDS).



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